



DMN3071LFR4

Product Summary

BV _{DSS}	R _{DS(ON)}	Ι _D T _A = +25°C
201/	65mΩ @ V _{GS} = 10V	3.4A
30V	75mΩ @ V _{GS} = 4.5V	3.0A

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- **Power Management Functions**
- Backlighting
- Load Switch

N-CHANNEL ENHANCEMENT MODE MOSFET

Features and Benefits

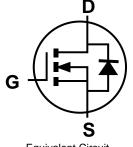
- Low On-Resistance
- Low Input/Output Leakage
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

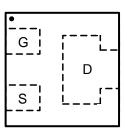
- Case: X2-DFN1010-3 •
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu over Copper Leadframe; Solderable per MIL-STD-202, Method 208 @
- Weight: 0.0015 Grams (Approximate)



Bottom View



Equivalent Circuit



Pin-out Top View

Ordering Information (Note 4)

Part Number	Case	Tape Width (mm)	Tape Pitch (mm)	Packaging		
DMN3071LFR4-7	X2-DFN1010-3	8	4	3000/Tape & Reel		
DMN3071LFR4-7R	X2-DFN1010-3	8	4	3000/Tape & Reel		
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS). 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.						

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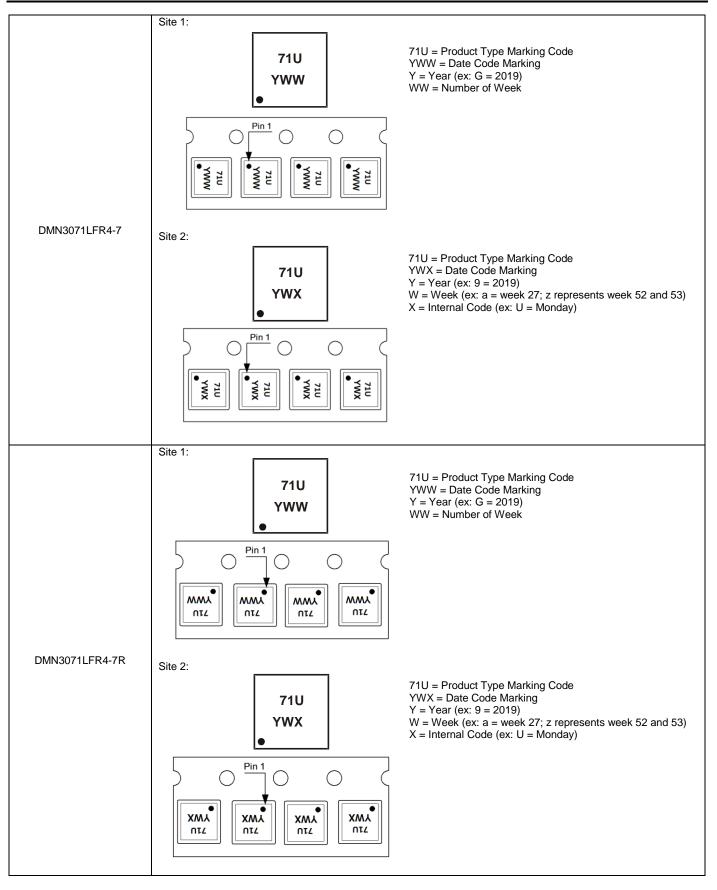
2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information





Marking Information (Cont.)

Site 1:

Year	2018	2019	2020	2021	2022	2023	2024	2025
Code	F	G	Н	I	J	K	L	М
2:								
2:								
2: Year	2018	2019	2020	2021	2022	2023	2024	2025

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	Ν	D
Week		1	-26			27	-52			5	3	
Code		/	۹-Z			а	-Z			:	Z	
1												
Internal Code	Sur	n	Mon		Tue	w	ed	Thu		Fri		Sat
Code	Т		U		V	V	V	Х		Y		Ζ



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V _{DSS}	30	V		
Gate-Source Voltage	V _{GSS}	±20	V		
Continuous Drain Current (Note 6) V_{GS} = 10V	Ι _D	3.4 2.7	A		
Maximum Continuous Body Diode Forward Current (ls	1.5	А		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	15	А

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		PD	0.5	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R _{0JA}	221	°C/W
Total Power Dissipation (Note 6)		PD	1.1	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R _{0JA}	107	°C/W
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C

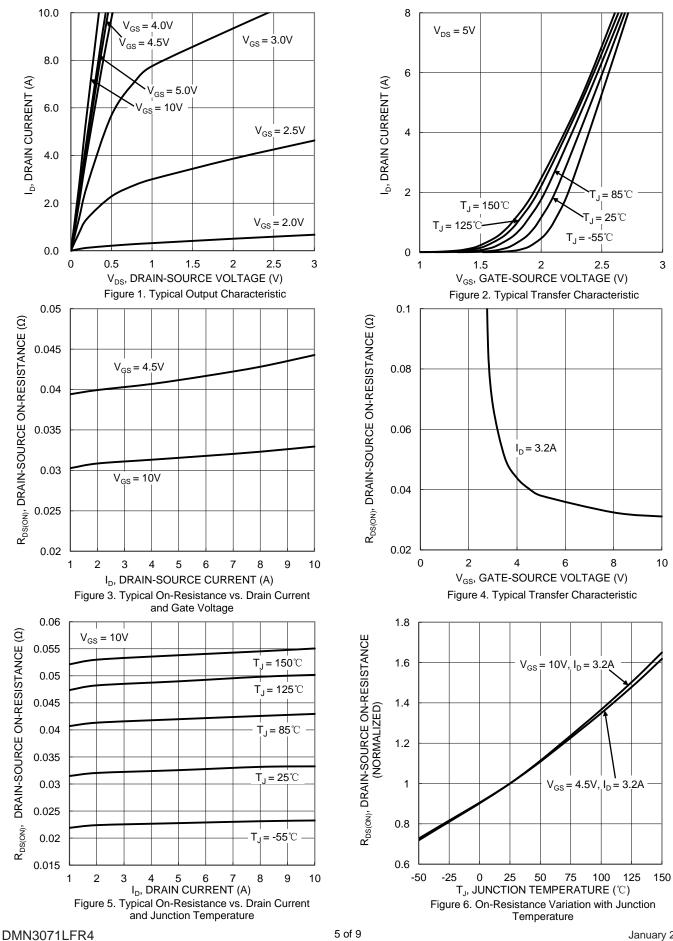
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)	.		- 71-				
Drain-Source Breakdown Voltage	BV _{DSS}	30	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}		—	1	μA	$V_{DS} = 30V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}		—	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)						·	
Gate Threshold Voltage	V _{GS(TH)}	1.0	_	2.5	V	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	
Static Drain-Source On-Resistance				65	mΩ	$V_{GS} = 10V, I_D = 3.2A$	
Static Dialit-Source Off-Resistance	R _{DS(ON)}	_	_	75	11152	$V_{GS} = 4.5V, I_D = 3.2A$	
Diode Forward Voltage	V _{SD}	—	0.8	1.2	V	$V_{GS} = 0V, I_S = 1A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C _{iss}	—	190	—			
Output Capacitance	C _{oss}	—	36	—	pF	$V_{DS} = 15V, V_{GS} = 0V$ f = 1.0MHz	
Reverse Transfer Capacitance	C _{rss}	—	26	-			
Gate Resistance	Rg	_	4.2	—	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	2.1	—			
Total Gate Charge (V _{GS} = 10V)	Qg	—	4.5	-	nC		
Gate-Source Charge	Q _{gs}	_	0.5	—	nc	$V_{DS} = 15V, I_D = 4A$	
Gate-Drain Charge	Q _{gd}		0.8	—			
Turn-On Delay Time	t _{D(ON)}	_	1.7	—			
Turn-On Rise Time	t _R	—	5.7	—		$V_{DS} = 15V, V_{GS} = 10V,$	
Turn-Off Delay Time	t _{D(OFF)}	_	6.0	—	ns	$R_G = 3\Omega$, $I_D = 4A$	
Turn-Off Fall Time	t _F		1.6	—			
Reverse Recovery Time	t _{RR}	—	4.2	_	ns		
Reverse Recovery Charge	Q _{RR}	_	0.5	_	nC	$I_F = 4A$, di/dt = 100A/µs	

 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.
Short duration pulse test used to minimize self-heating effect.
Guaranteed by design. Not subject to production testing. Notes:



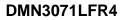
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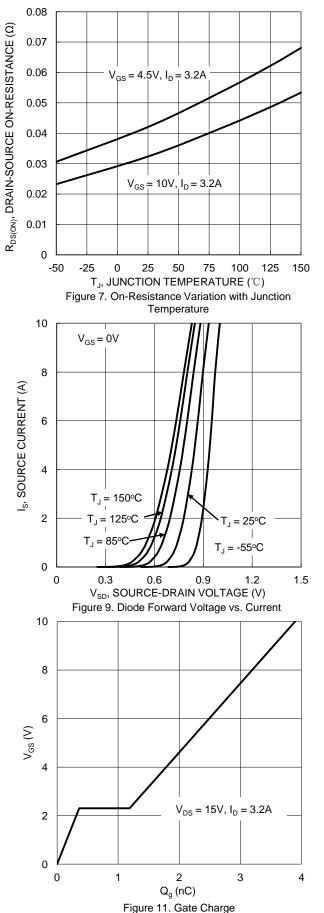


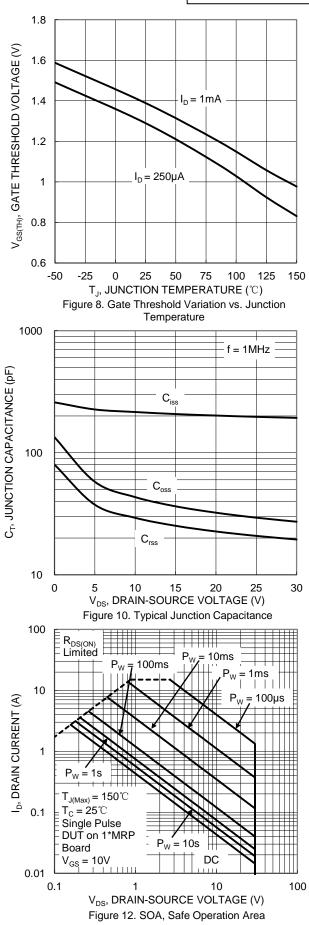
Document number: DS40749 Rev. 2 - 2

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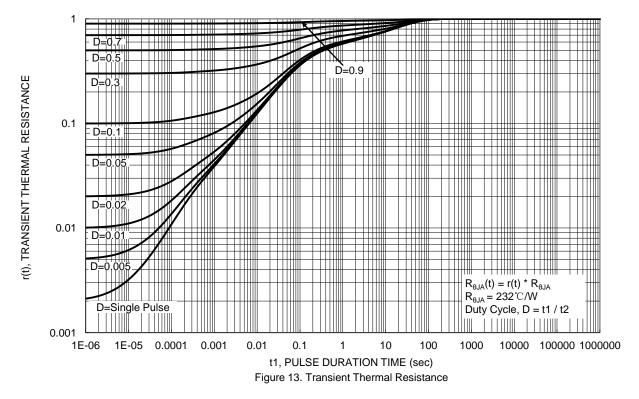




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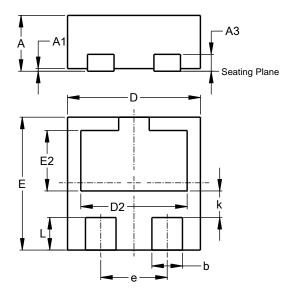


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1010-3

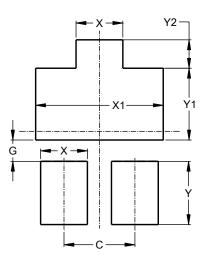
X2-DFN1010-3



	X2-DFN1010-3							
Dim	Min	Max	Тур					
Α	-	0.40	0.39					
A1	0.00	0.05	0.02					
A3	-	-	0.13					
b	0.18	0.28	0.23					
D	0.95	1.05	1.00					
D2	0.70	0.90	0.80					
Е	0.95	1.05	1.00					
E2	0.36	0.56	0.46					
е	-	-	0.50					
k	-	-	0.20					
L	0.195	0.295	0.245					
Α	II Dimen	sions in	mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions
С
C

С	0.500
G	0.150
X	0.330
X1	0.900
Y	0.445
Y1	0.505
Y2	0.200

Value (in mm)



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